



Product End-of-Life Disassembly Instructions

Product Category: Monitors and Displays

Marketing Name / Model
[List multiple models if applicable.]

HP Pavilion 27xw 27-in IPS Monitor

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

| Item Description | Notes | Quantity of items included in product |
|--|---|---------------------------------------|
| Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA) | With a surface greater than 10 sq cm | 2 |
| Batteries | All types including standard alkaline and lithium coin or button style batteries | 0 |
| Mercury-containing components | For example, mercury in lamps, display backlights, scanner lamps, switches, batteries | 0 |
| Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm | Includes background illuminated displays with gas discharge lamps | 1 |
| Cathode Ray Tubes (CRT) | | 0 |
| Capacitors / condensers (Containing PCB/PCT) | | 7 |
| Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height | | 0 |
| External electrical cables and cords | | 3 |
| Gas Discharge Lamps | | 0 |
| Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above) | | 0 |
| Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner | Include the cartridges, print heads, tubes, vent chambers, and service stations. | 0 |
| Components and waste containing asbestos | | 0 |
| Components, parts and materials containing | | 0 |

| | | |
|---|--|---|
| refractory ceramic fibers | | |
| Components, parts and materials containing radioactive substances | | 0 |

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

| Tool Description | Tool Size (if applicable) |
|---|---------------------------|
| Description #1 SCREW DRIVER(Plum flower head) | |
| Description #2 | |
| Description #3 | |
| Description #4 | |
| Description #5 | |



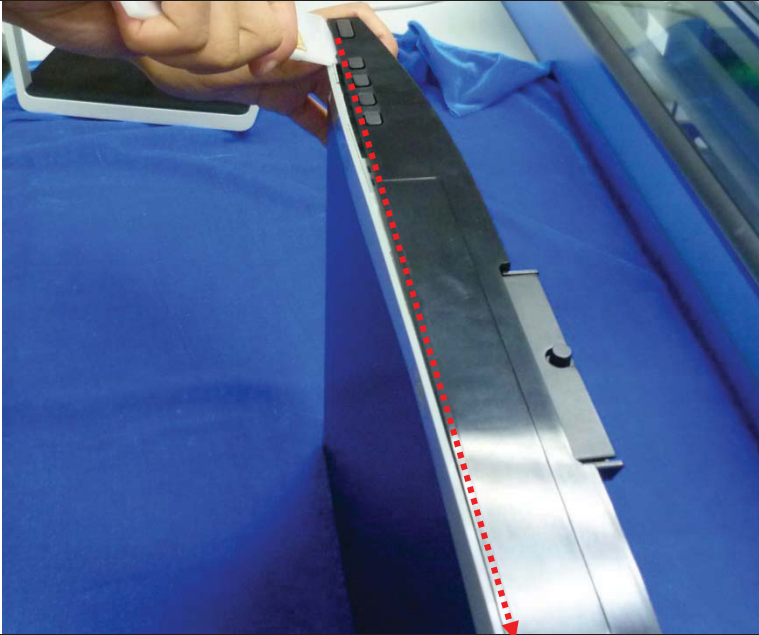
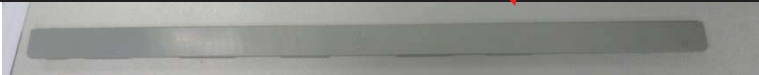
3.0 Product Disassembly Process



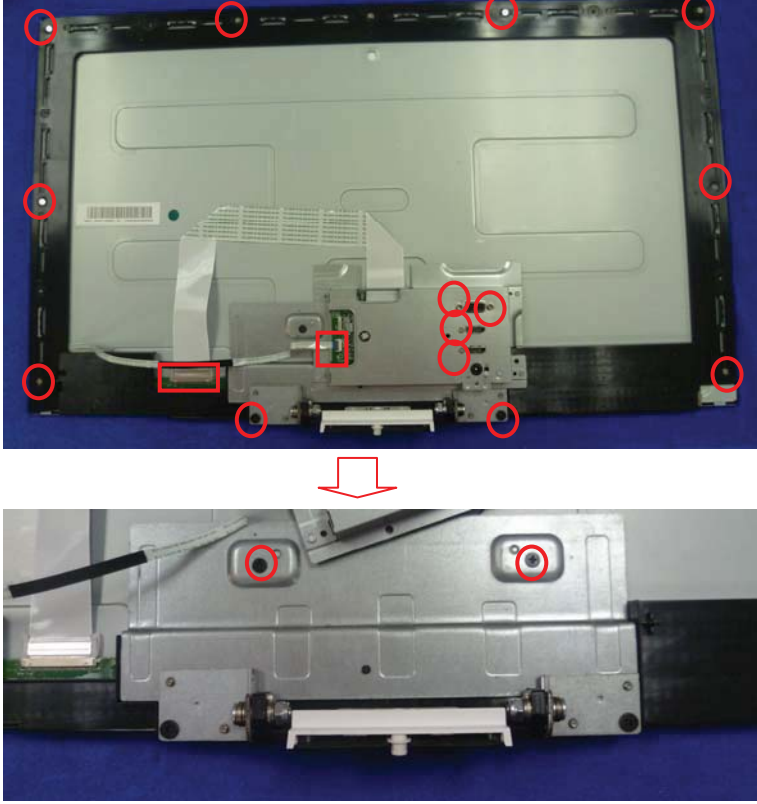
3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Dismantle the hinge assy.
2. Dismantle the bezel deco of monitor.
3. Dismantle the back cover of monitor.
4. Dismantle the keyboard from back cover.
5. Dismantle the screws from Mainframe.
6. Pull out the PIN of FFC cable, separate the mainframe and Panel.
7. Dismantle the PCBA screws.
8. Take off board.

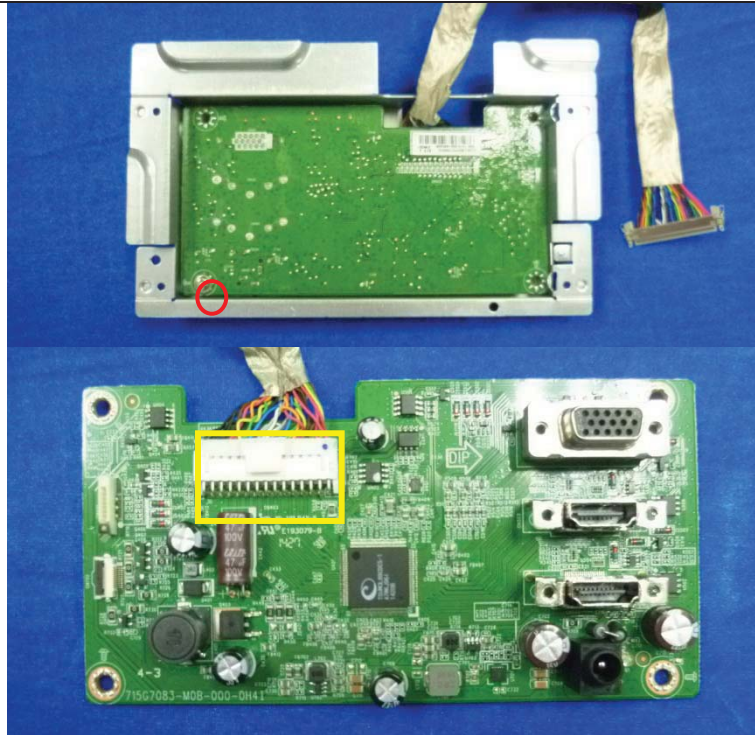
3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

11. Mechanical Instructions

| Step | Figure | Description |
|--------------------------------------|--|---|
| <p>Remove the HINGE ASS'Y</p> |  | <p>Press the button to remove the hinge assy Unscrew the screw.</p> |
| <p>The HINGE ASS'Y</p> |  | <p>The HINGE ASS'Y</p> |
| <p>Remove the BEZEL</p> |  | <p>Use the tool to remove the Bezel</p> |
| <p>The BEZEL</p> |  | <p>The BEZEL</p> |

| | | |
|---|--|---|
| <p>Remove the REAR_COVER</p> |  | <p>Use the tool to remove the rear cover</p> |
| <p>Remove the key board</p> |  | <p>Remove the screw the key board</p> |
| <p>Separate the MAINFRAME and PANEL</p> |  | <p>Tear out all tapes. Remove the screws and disconnect the connectors to separate the MAINFRAME and PANEL.</p> |

Remove the
MAIN BOARD
and POWER
BOARD





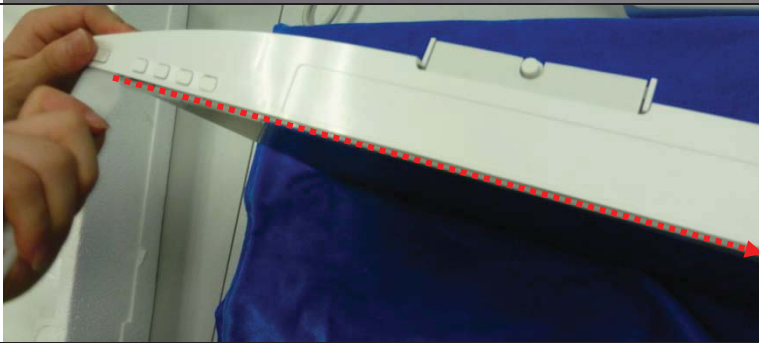

Remove the
screws and
disconnect the
connectors to
remove the
MAIN BOARD



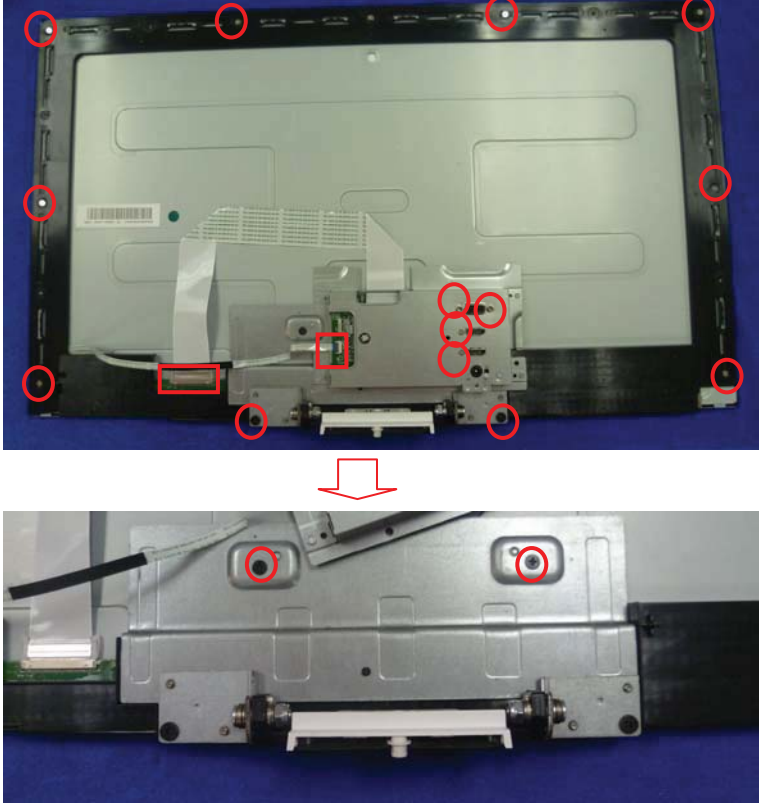
The panel



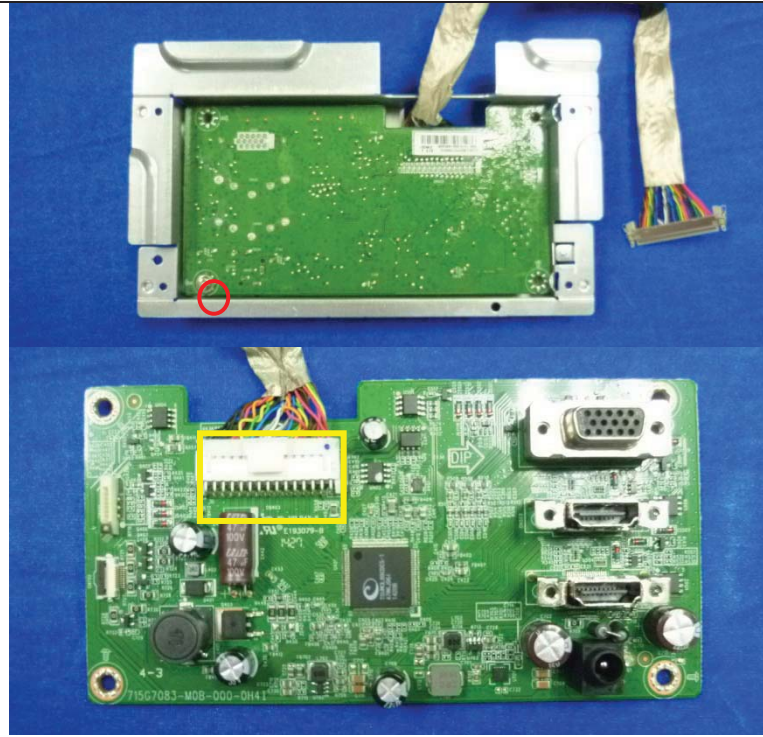
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| <p>Remove the BEZEL</p> |  | <p>Use the tool to remove the Bezel</p> |
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| | | |
|--|--|---|
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Remove the
MAIN BOARD
and POWER
BOARD



Remove the
screws and
disconnect the
connectors to
remove the
MAIN BOARD

The panel



The panel